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Suppl. Amndt c
J. Robinson
5/29/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: OPTOELECTRONIC SEMICONDUCTOR PACKAGE DEVICE
Serial No.: 10/082,500 Filed: February 25, 2002
Examiner: Chu, C. Group Art Unit: 2815
Atty. Docket No.: BDG005-3

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SUPPLEMENTAL RESPONSE

In further response to the Office Action dated April 10, 2003, please amend the application as follows.

In the Claims

Amend the following claims:

1 C) 21. (Twice Amended) An optoelectronic semiconductor package device, comprising:
2 a semiconductor chip that includes an upper surface, a lower surface and four outer side
3 surfaces between the upper and lower surfaces, wherein the upper surface includes a light
4 sensitive cell and a conductive pad;
5 an insulative housing that includes a top surface, a bottom surface and uncurved
6 peripheral side surfaces between the top and bottom surfaces, wherein the insulative housing
7 further includes first and second insulative housing portions, the first housing portion is a single-
8 piece that provides the bottom surface and is non-transparent, and the second housing portion